The 1809 EXL Reflow System

- Compatible with both eutectic and lead-free alloys
- Lowest cost of ownership
- High reliability
- Best overall value

The 1809 EXL supports high mix / high volume throughput... at speeds up to 32 inches (80 centimeters) per minute, while conserving valuable factory floor space. Rapid response times and precise temperature controls assure process uniformity, regardless of component density or board loading, with identical profile performance in either air or nitrogen.

The Model 1809 EXL combines sophisticated design elements with the engineering expertise and reflow technology leadership you’ve come to expect from Heller Industries:

**Highest Yields and Tight Process Control**
- The most efficient heat transfer from extra high volume, high-velocity, heating modules, producing heater module response of less than one second to temperature changes of less than $0.1^\circ C$, thereby maintaining profile integrity for heavy board loads.
- Wide process window for “universal profiling” — allows many different boards to be run on a single temperature profile
- Included with every system:
  - Advanced 5 thermocouple PCB profiling and process parameter logging capability with the capacity to store up to 500 temperature recipes and 500 profile graphs
  - Cpk software — “real-time” Cpk calculation shows oven performance and repeatability and gives Cpk data for each zone and the entire oven — a Heller exclusive!

**Lowest Cost of Ownership**
- Computer-controlled automatic lubrication system for “hands-off” maintenance
- Optional flux separation system removes up to 95% of flux from the oven tunnel — virtually eliminating maintenance and protecting the environment
- Pure forced convection design saves nitrogen — with consumption levels as low as 700 SCFH at 500 PPM*
- Low KW design saves electricity and reduces warm up and profile changeover time

* Depends on board width and vertical clearance

Integrated “real-time” Cpk software provides instant process data — at no additional charge!

Pure convection technology provides flexibility to produce any solder paste manufacturer’s recommended profile.
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With a high-capacity, 26-inch wide heater module, the 1809 EXL offers unmatched flexibility in board handling. The oven may be fitted with an adjustable single-rail edge hold conveyor/mesh belt combo, to carry even the largest boards or multi-board panels (up to 20 inches wide) through the oven.